Recommendations/Comments for “IPC 2226”
(Implementation subject to customer/supplier agreement)

Objective:
- Increase the reliability of electronic components
- Reduce the risk of copper bond failure due to thermal stress during the soldering process

Source: Bill Birch, PWB Interconnect Solutions Inc.
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Excerpt from IPC 2226:

Figure 5-4 Type III HDI Construction with Stacked Microvias
(Caution: Unbalanced constructions as shown above may result in excessive bow and twist.)

Note 1: Stacking not recommended for resin or conductive/non-conductive filled microvias.
Note 2: Stacking not recommended over resin or conductive/non-conductive filled vias due to potential for reduced reliability. The use of staggered structures instead is recommended.

Caution: HDI design with microvias stacked on buried vias is not recommended.

PCB and Electronic Systems Division within the German Electrical and Electronic Manufacturers’ Association,
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Recommendations for implementing IPC 2226:
Arranging stacked and resin-filled buried vias in a staggered layout.

Comment:
The copper cap of the resin-filled vias may be dispensed with if necessary.